

LOW PROFILE LATCH ACTIVATOR

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LOW PROFILE LATCH ACTIVATOR

Field Of The Invention

The present technique relates generally to the field of computer systems and, more specifically, to a unique latch and release mechanism for a modular device. The present 5 technique comprises a movable tool-less release assembly for simultaneously releasing a latch and removing the modular device from a receptacle.

Background of the Invention

Computer systems generally include a computer housing having a motherboard, a 10 processor, a hard drive, random access memory (RAM), a disk drive (e.g., a floppy drive, a CD-ROM drive, a DVD-ROM drive, a tape drive, etc.), communication ports, a cooling system (e.g., a fan), a power supply, a modem, a network device, an audio assembly (e.g., a sound card, a speaker, etc.), and various other devices. Many of these devices have a modular housing or structure, which is removably inserted into a device slot in the computer 15 system. In desktop computers, these modular devices are typically attached to the computer chassis via screws. In portable computers, these modular devices may be attached via screws or a combination of latches and release mechanisms. For example, the modular device may have a lever to release a latch mechanism, while the portable computer has a lever to push the modular device out of the device slot. In servers and other large-scale 20 systems, a plurality of modular devices may be inserted into adjacent slots, making it difficult to use any sort of quick release mechanism. For example, the server may have

multiple fans disposed side by side. Due to limited space, lateral latch and release mechanisms may not be possible for such a configuration.

Accordingly, a technique is needed for releasing a modular device from an
5 accessible side of the modular device. More particularly, it would be advantageous to provide a tool-free release assembly, which may be activated to release a tool-free latch assembly for the modular device. It would also be advantageous to incorporate a device release mechanism into the tool-free release assembly to facilitate physical removal of the modular device from a receptacle.

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SUMMARY OF THE INVENTION

A technique is provided for coupling and uncoupling modular devices with electronic and computing devices. A latch is coupled to a release member, which operates to release the latch from a mate latch by bending the release member to move the
15 latch laterally away from the mate latch. The release member also may have grips for tool-lessly bending the release member to release the latch from the mate latch, and for removing the desired device. The technique also may embody a modular device having the latch and release member, or it may embody an overall system having the modular device disposed in a receptacle.

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In one aspect, the present technique provides an attachment system for a modular component of a computing device. The attachment system comprises a latch member having a mechanical latch and a flexible release member movably coupled to the latch member. The flexible release member also includes a grip for bending the flexible release member to effectuate a movement of the mechanical latch to a released position.

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In another aspect, the present technique provides a modular component for a computer system. The modular component comprises a modular housing having an accessible side and a lateral side. A flexible and graspable release member is coupled to the accessible side, while a low profile latch is coupled to the lateral side. The flexible and graspable release member is also movably coupled to the low profile latch between the accessible and lateral sides.

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In another aspect, the present technique provides a method of forming a tool-free connector for modular computing components. The method comprises providing a first flexible member having a latch and providing a second flexible member having a finger grip. The method also includes rotatably coupling free ends of the first and second flexible members to facilitate release of the latch.

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BRIEF DESCRIPTION OF THE DRAWINGS

The invention will hereafter be described with reference to the accompanying drawings, wherein like reference numerals denote like elements, and:

5 Figure 1 is a perspective view of an exemplary system incorporating unique attachment and release mechanisms of the present technique;

Figure 2 is a perspective view of an exemplary modular device exploded from a receptacle of the system;

Figure 3 is a side view of the modular device latched within the receptacle;

Figure 4 is a side view of the modular device being unlatched from the receptacle;

10 Figure 5 is a perspective view of the modular device being physically removed from the receptacle;

Figure 6 is a perspective view of an exemplary embodiment of the modular device as a cooling assembly;

15 Figure 7 is a perspective view of an alternate embodiment of the system having a status indicator disposed in the receptacle;

Figure 8 is a perspective view of an alternate embodiment of the system having the status indicator coupled to the modular device;

Figure 9 is a side view of an alternate embodiment of the system having the modular device and the status indicator disposed in the receptacle;

20 Figure 10 is a top view of the modular device and the status indicator illustrated in Figure 9;

Figure 11 is a perspective view of an exemplary movable connector for the system;

Figure 12 is a perspective view of an exemplary movable connector and attachment members for the system; and

5 Figure 13 is a side view of the movable connector and attachment members illustrated in Figure 12.

DETAILED DESCRIPTION OF SPECIFIC EMBODIMENTS

As described in detail below, the present technique provides a unique latch and release mechanism, which may be utilized in a variety of electronics and computing devices, such as desktop computers, laptops, notebooks, PDAs, servers, or any other desired device. An exemplary system 10 in accordance with certain aspects of the present technique is illustrated in Figures 1 and 2, which are perspective views of a modular device 12 inserted into, and removed from, a receptacle 14 of an electronic device 16.

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As discussed in detail below, the modular device 12 may embody any desired electrical mechanical device, such as a disk drive (e.g., a CD-drive, a DVD-drive, a CD RW drive, a floppy drive, a hard drive, etc.), a fan or cooling module, a memory module, a processor module, a device card (e.g., an ISA card, an EISA card, a PCI card, a PCMCIA card, etc.), a power supply module, a circuit board, and various other electrical, mechanical and computing modules. The receptacle 14 may embody a single device slot

or bay, a multidevice receptacle, an electrical connection slot or plug, or any other suitable receptacle. The electronic device 16 may embody any desired electrical, mechanical or computing device, including those devices and systems described above. Moreover, the present technique may embody the entire electronic device 16, the modular device 12, or it may simply embody the unique latching and release features illustrated and described in the following Figures. The system 10 and modular device 12 also may include various circuitry, software and components to facilitate insertion and removal of the modular device 12 during operation of the electronic device 16. For example, hot-plug circuitry and software maybe integrated into the system 10 and/or the modular device 12.

As illustrated in Figures 1 and 3, the modular device 12 is coupled to the receptacle 14 via a latch assembly 18, which has a latch structure 20 disposed on a movable latch member 22. The movable latch member 22 may embody a flexible structure, such as a flexible plastic or metal, or it may embody any other suitable laterally activated latch mechanism. For example, the latch assembly 18 may comprise a spring assembly, a linear positioning assembly, or other laterally movable mechanisms to facilitate movement of the latch structure 20 inwardly and outwardly from the modular device 12. However, in this exemplary embodiment, the movable latch member 22 embodies a flexible structure. The movable latch member 22 is coupled to a lateral section 24 of the modular device 12 via connectors 26, which may embody screws, rivets,

adhesive, welding or any other suitable connection mechanism. The movable latch member 22 may be coupled to the lateral section 24 in any suitable location to facilitate movement (i.e., bending and linear movement) of the movable latch member 22 and the corresponding latch structure 20. In the mounted orientation of Figure 1, the latch structure 20 is removably coupled to a mating latch structure 28 disposed in the receptacle 14. This latch connection is released by engaging a release assembly 30 (see Figures 4 and 5), which is disposed on an accessible section 32 of the modular device 12.

5 As illustrated in Figures 1 and 2, the release assembly 30 is rotatably coupled to the modular device 12 via hinge structures 34. The release assembly 30 is also rotatably coupled to the latch assembly 18 via a hinge structure 36, which is formed between the latch and release assemblies 18 and 30 at an edge 38 between the lateral and accessible sections 24 and 32, respectively. As illustrated, the hinge structure 36 is formed by a loop portion 24 of the movable latch member 22 being wrapped around a rod portion 46 of the release assembly 30. However, the hinge structures 34 and 36 may embody any suitable movable joints or hinges, such as a pin and hole mechanism, a rod and loop mechanism, a ball and socket mechanism, or any other mechanisms. In this exemplary embodiment, the release assembly 30 also embodies a flexible material, such as a flexible plastic or metal, and includes grips 40 and 42 to facilitate bending of the release assembly 30. For 10 example, the grips 40 and 42 may be used to flex the release assembly 30 to a desired bent geometry, such as a U-shaped geometry, a concave geometry, a convex geometry, an 15 20

S-shaped geometry, or a partially bent geometry, thereby moving at least one end of the release assembly 30.

Accordingly, as illustrated in Figures 3 through 5, the modular device 12 may be
5 removed from the receptacle 14 by engaging the release assembly 30 to release the latch connection and physically remove the modular device. In an unbent orientation of the release assembly 30, the latch structure 20 is interlocked with the mating latch structure 28, as illustrated by the cross-sectional side view of Figure 3. An electrical connection is also formed between electrical connectors 48 and 50, which are disposed on the modular
10 device 12 and a circuit board 52 of the electronic device 16, respectively. The electrical connection provides power and any other desired control signals for the modular device 12. One or both of the electrical connectors 48 and 50 also may have a semi-loose mount mechanism to facilitate a smooth mount and dismount, mate and unmate (e.g., a blind
15 mating mechanism) of the modular device 12 and corresponding electrical connection formed by the electrical connectors 48 and 50. It also should be noted that the flexible embodiments of the latch and release assemblies 18 and 30 provide a spring force to ensure that the latch structure 20 remains interlocked with the mating latch structure 28.

This latch connection is released by engaging the release assembly 30, as
20 illustrated by the cross-sectional side view of Figure 4. As a user 54 engages the grips 40 and 42 and pulls the release assembly 30 upwardly away from the receptacle 14, as

indicated by arrow 56, the release assembly 30 bends between the hinge structures 34 and 36 and a free end 58 of the release assembly 30 moves along an edge 60 of the accessible section 32. The release assembly 30 may be partially or fully bent to a curved geometry, such as a u-shaped geometry, an n-shaped geometry, or a concave or convex geometry.

5 The foregoing movement of the free end 58 also causes the movable latch member 22 to move inwardly away from the mating latch structure 28. Accordingly, the movable latch member 22 is laterally activated or operated (i.e., engaged or released) by the release assembly 30, which is outwardly bendable or bowable in at least a portion of the release assembly 30. As the movable latch member 22 is moved inwardly, the latch structure 20
10 is released from the mating latch structure 28, as illustrated in Figure 4. The modular device 12 is then removed from the receptacle 14 by continuing to pull upwardly with the grips 40 and 42, as illustrated by the perspective view of Figure 5 and indicated by arrow 62. At the same time, the electrical connector 48 disengages from the electrical connector 50. Finally, the modular device 12 is completely dismounted from the receptacle 14 of
15 the electronic device 16, as illustrated in Figure 2. It also should be noted that the latch and release assemblies 18 and 30 may embody any suitable bendable or movable structures, such as inwardly/outwardly movable, flexible, bowable, or bendable structures.

20 As mentioned above, the modular device 12 may embody a variety of electrical, mechanical, and computing components within the scope of the present technique. For

example, the modular device 12 may embody a cooling or fan assembly 64, as illustrated by the perspective view of Figure 6. In this exemplary embodiment, an airflow grill 66 is disposed on opposite sides of the modular device 12, while a cooling or fan device is disposed within the modular device 12. The unique aspects of the latch and release assemblies 18 and 30 allow a plurality of these cooling or fan assemblies 64 to be mounted side-by-side in the desired electronic device 16, thereby increasing the overall cooling capacity for the desired electronic device 16.

5 The system 10 also may comprise various other electrical, mechanical, and computing features, such as illustrated in Figures 7 through 10. For example, the system 10 may include a status indicator 68 for the modular device 12. This status indicator 68 may be incorporated into the receptacle 14 as illustrated in Figure 7, into the modular device 12 as illustrated in Figure 8, or into any desired location within the electronic device 16. Depending on the features of the modular device 12, the status indicator 68 15 may provide a power status, a free/busy status, or any other desired operational status. Moreover, the status indicator 68 may include one or more status indicator lights 70 disposed in any of the foregoing positions. The status indicator 68 also may embody a signal transmission assembly 72, such as a light pipe or electrical circuitry, for transmitting a status signal from an adjacent indicator light or circuit board. The signal 20 transmission assembly 72 may be disposed along the depth of the modular device 12 or along the receptacle 14, as illustrated in Figures 7 and 8, respectively. In either

configuration, an indicator light or circuitry (e.g., an electrical plug, a wireless connector such as a fiber optic connector, a spring-loaded electrical contactor assembly, etc.) may be disposed at a base of the receptacle 14 to transmit a desired status signal to the user in a desired viewing location, such as the accessible section 32 of the modular device 12. For 5 example, the desired status signal may be transmitted from the circuit board 52, through the electrical connectors 48 and 50, and to the status indicator light 70 via the signal transmission assembly 72.

In the foregoing embodiments of Figures 7 and 8, the latch and release assemblies 10 18 and 30 operate essentially as described above with reference to Figures 1 through 5. As illustrated in the cross-sectional side view and the top view of Figures 9 and 10, the status indicator 68 is disposed adjacent the structure of the modular device 12, such that the status indicator 68 does not interfere with the operation of the latch and release assemblies 18 and 30. However, incorporation of the status indicator 68 may require 15 widening of the receptacle 14 or narrowing of the modular device 12. At a base 74 of the receptacle 14, the system 10 also may include a signal source 76 (e.g., a status light or electrical connector) disposed on the circuit board 52. For example, if the signal source 76 embodies a status light, then it would be positioned adjacent the signal transmission assembly 72 (e.g., a light pipe). A status signal may then be transmitted through the 20 signal transmission assembly 72 to the status indicator light 70, which is viewable at the accessible section 32.

As mentioned above, the electrical connectors 48 and 50 may have a semi-loose mount mechanism to facilitate a smooth mount and dismount, mate and unmate (e.g., a blind mating mechanism) of the modular device 12 and the corresponding electrical connection formed between the electrical connectors 48 and 50. For example, the 5 electrical connector 48 may be disposed on a movable base 78 and have a substantially smaller geometry than a housing opening 80 in the modular device 12, as illustrated by the perspective view of Figure 11. Accordingly, the electrical connector 48 may move within the housing opening 80, while the movable base 78 secures the electrical connector 48 within the modular device 12. The system 10 also may have movable 10 attachment members to secure the movable base 78 to the modular device 12, as illustrated by the perspective view and side view of Figures 12 and 13, respectively. For example, tool free attachment members 82 may be coupled to the movable base 78 and extended through housing openings 84. In this exemplary embodiment, the tool free attachment members 82 have flexible wings 86 (e.g., conic-shaped wings) coupled to a 15 central rod 88. The movable base 78 and the electrical connector 48 may then be removed from the modular device 12 by squeezing the flexible wings 86 and pushing the electrical connector 48 and tool-free attachment members 82 through the housing openings 80 and 84, respectively. Any other suitable movable attachment mechanism also may be used within the scope of the present technique. Moreover, the present 20 technique may provide a reduced friction surface, a slider/drawer mechanism, a bearing mechanism, beveled connection edges, or a desired degree of tolerance between the

modular device 12 and the receptacle 14 and between the electrical connectors 48 and 50 to facilitate a smooth intercoupling between the respective components, rather than using the foregoing moveable connection mechanism.

5 While the invention may be susceptible to various modifications and alternative forms, specific embodiments have been shown by way of example in the drawings and have been described in detail herein. However, it should be understood that the invention is not intended to be limited to the particular forms disclosed. For example, the present technique may be applied to a variety of computing systems, computing components, and other electronic and computing devices, each having various components and features.

10 Moreover, a broad spectrum of electronic and communication technologies can be employed within the scope of the present technique. For example, wireless communication, blue tooth technologies, optical and digital technologies, and other emerging technologies are all within the scope of the present technique. Accordingly, the invention is intended to cover all modifications, equivalents, and alternatives falling 15 within the spirit and scope of the invention as defined by the following appended claims.